

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAB2003
Package Type :	PDFNWB3.3x3.3-8L-B
Part Description :	30V SMDs/MOSFET
Report Date:	February-25

2. Reliability Test Results : PASS

Test Item	Test condition	Duration	Fail Quantity / S.S
Pre-and post-stress Electrical test	Ta=25°C	NA	All parts
PC Precondition(For SMD Package Only)	JESD22-A113F/J-STD-020 1.Bake:125°C. 2.Soak: 85°C85%RH,168hrs MSL1 or 30°C60%RH,192hrs MSL3 3.Reflow 3Cycles Max 260°C 4.all samples E-Test	>168Hours or >192Hours	0 / 308
TCT Temperature Cycling Test	JESD22 -A104 -55°C/15min 150°C/15min	1000cycles	0 / 77
AC Autoclave	JESD22-A102 121°C, 100%RH	96Hours	0 / 77
UHA Unbiased Highly Accelerated Stress Test	JESD22-A118 130°C, 85%RH	96Hours	NA
HT High Humidity &Temp Test	JESD22-A101 85°C 85%RH	1000Hours	0 / 77
HTST High Temperature Storage Test	JESD22 -A103 T=Tstg max	1000Hours	0 / 77
H3TRB High Humidity &Temp . Bias Test	JESD22-A101 85°C 85%RH VDS*80% VR<=100V Max	1000Hours	NA
HAST Highly Accelerated Stress Test	JESD22-A110 130°C 85%RH VDS*80% VR≤42V Max	96Hours	0 / 77
HTRB High Temperature Revers Bias Test	JESD22 -A108 Tj(max) @VDS *80%	1000Hours	0 / 77
HTGB High Temperature Gate Bias Test	JESD22 -A108 Tj(max) VR=BVGS*100%	1000Hours	0 / 77
IOL Intermittent Operational Life	MIL-STD-750D Method 1037 ΔTj≥100°C On/Off:2min	15000Cycle	0 / 77
RSH Resistance to Solder Heat test	JESD22-A111B 260°C±5°C, 10(+2,-0)Seconds	NA	0 / 30
SD Solderability	J-STD-002 Steam aging:93°C 8hour 2.245°C 3~5s	NA	0 / 10

Notes:

1. Either H3TRB or HAST for reliability test.
2. Either AC or UHA for reliability test.
3. Detailed MSL of the product refers to the MSL Report.

Remark: JSCJ Laboratory reserves the right of final interpretation of this report